Face Down Expander

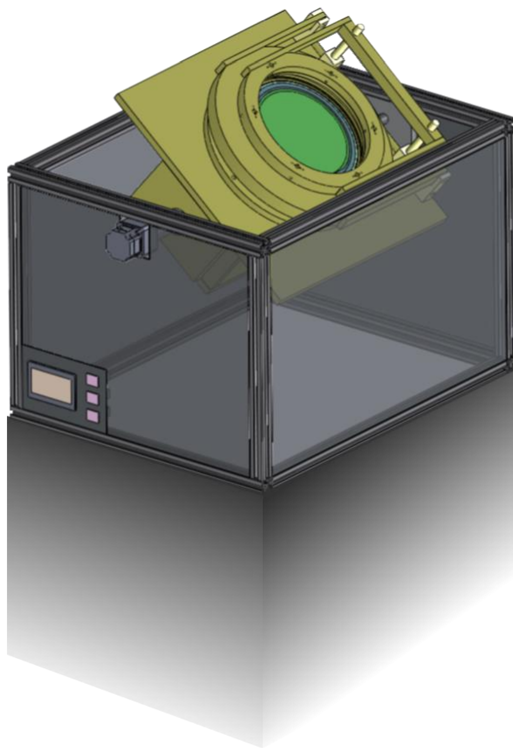
(Model MEX-200 / 300)

***Si-particle Free** Die separation after Stealth-Dicing for MEMS Wafers*

In Die separation process after stealth-dicing, silicon particle can be generated from side walls of the chips when they are separated. That Si-particle may disperse and fall onto not only the tape but also the surface of MEMS device. This causes serious quality issue.

Face Down Expander with anti-static functions prevent from Si-particle to disperse, and the Si-particle fall down by it gravity in negative pressure process chamber.

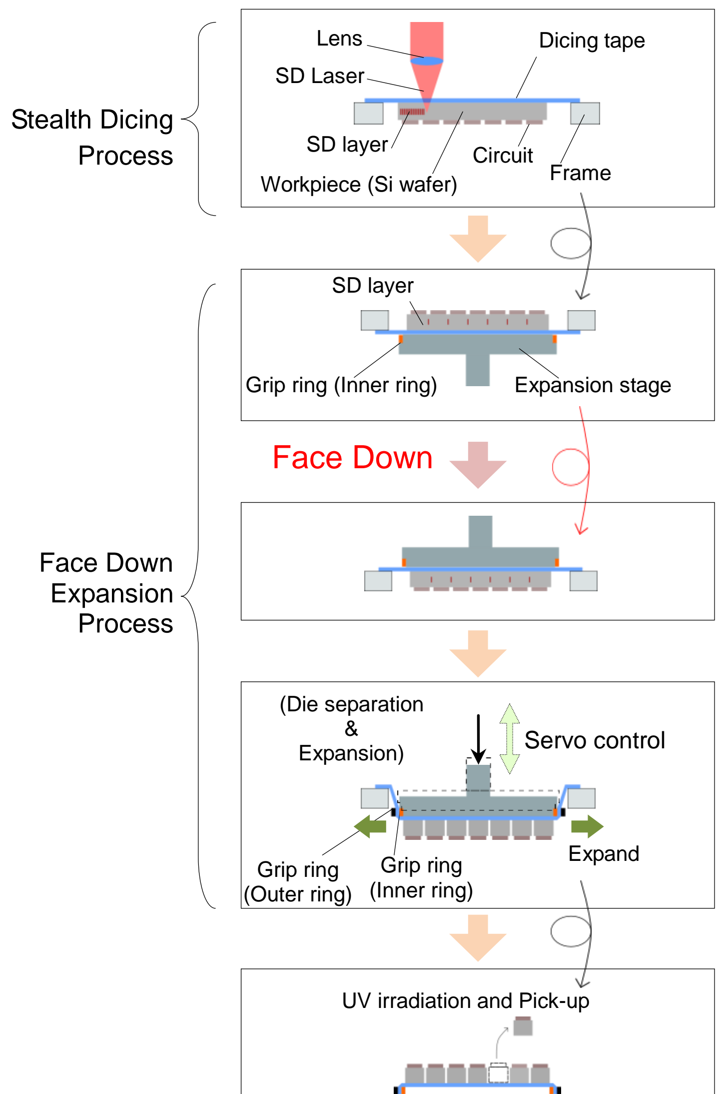
■ Outside Image Drawing



(* For illustrative purposes only)

MEX-200 : Up to 8" / 200mm model
MEX-300 : Up to 12" / 300mm model

■ Expansion Process



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